



### Contact EoPlex

1321 Ridder Park Drive, Suite 10  
 San Jose, CA 95131  
 408.638.5100  
 info@eoplex.com

# CSI™ Extreme

## Preliminary Product Brief

### Overview

The CSI™ Extreme is the competitive edge for high lead count, complex applications with strict cost, size, and performance requirements.

The unique printed nature of the product enables QFN packages with high pin count that otherwise require bulky and more expensive technologies such as QFP or BGA. The CSI™ Extreme is particularly useful for applications in mobile computing and communications devices.

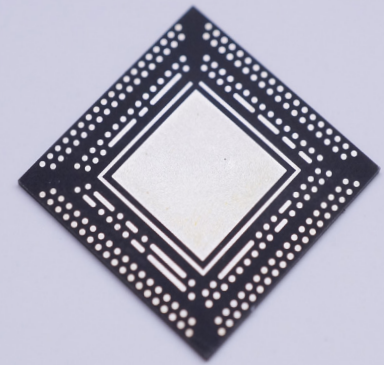
The below data is for reference only. For detailed analysis on specific packages, contact EoPlex at info@eoplex.com.

### Thermal Performance

Lead Count	Package Size (mm)	DAP Size (mm)	θJA (°C/W)		
			0 m/s	1 m/s	2 m/s
132	10 x 10	7.00	17.30	15.27	13.26
224	12 x 12	6.60	16.20	14.18	12.17

### Electrical Performance

Lead Count	Package Size (mm)	DAP Size (mm)	Ls(nH)	Lm(nH)	C(pf)	Cm(pf)
132	10 x 10	7.00	1.45	0.71	0.22	0.06
224	12 x 12	6.60	1.60	0.82	0.24	0.06



### Highlights

- Printed Components
- I/O Range, > 88 Leads
- Multi-Row I/O
- Multiple power domains
- Thin package, 0.25 mm
- Custom Design Flexibility
- Green Process

### Specifications

- Wire Bond: Gold or Copper
- Lead Finish: Sintered Silver
- Bond Pad Pitch: > 0.2mm

### Application Areas

- High Lead Applications
- Mobile Devices
- Disk Drives
- Tablets
- Smartphones